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LM340-MIL Wide V_{IN} 1.5-A Fixed Voltage Regulator

1 Features

- Output Current up to 1.5 A
- Available in Fixed 5-V, 12-V, and 15-V Options
- Internal Thermal Overload, Short-Circuit and SOA Protection
- Available in Space-Saving SOT-223 Package
- Output Capacitance Not Required for Stability

2 Applications

- Industrial Power Supplies
- SMPS Post Regulation
- HVAC Systems
- AC Inventors
- Test and Measurement Equipment
- Brushed and Brushless DC Motor Drivers
- Solar Energy String Invertors

3 Description

The LM340-MIL monolithic 3-pin positive voltage regulators employ internal current-limiting, thermal shutdown and safe-area compensation, making them essentially indestructible. If adequate heat sinking is provided, they can deliver over 1.5-A output current. They are intended as fixed voltage regulators in a wide range of applications including local (on-card) regulation for elimination of noise and distribution problems associated with single-point regulation. In addition to use as fixed voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents.

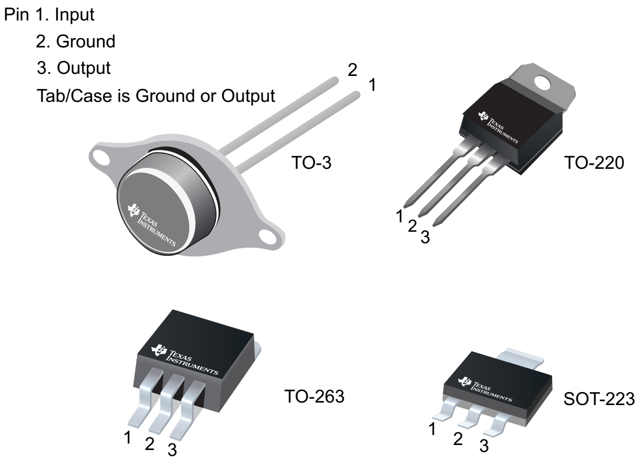
Considerable effort was expended to make the regulator easy to use and minimize the number of external components. It is not necessary to bypass the output, although this does improve transient response. Input bypassing is needed only if the regulator is located far from the filter capacitor of the power supply.

Device Information(1)

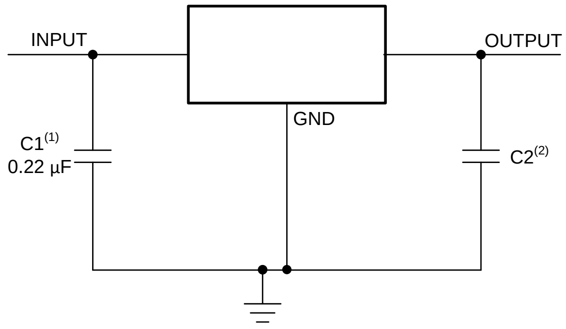
PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM340-MIL	TO-3 (2)	38.94 mm x 25.40 mm
	TO-220 (3)	14.986 mm × 10.16 mm
	DDPAK/TO-263 (3)	10.18 mm × 8.41 mm
	SOT-23 (4)	6.50 mm × 3.50 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Available Packages



Fixed Output Voltage Regulator



(1) Required if the regulator is located far from the power supply filter.

(2) Although no output capacitor is needed for stability, it does help transient response. (If needed, use 0.1-µF, ceramic disc).

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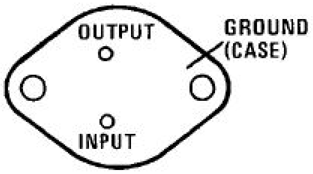
4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

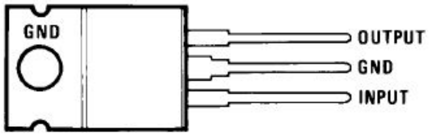
DATE	REVISION	NOTES
June 2017	*	Initial release.

5 Pin Configuration and Functions

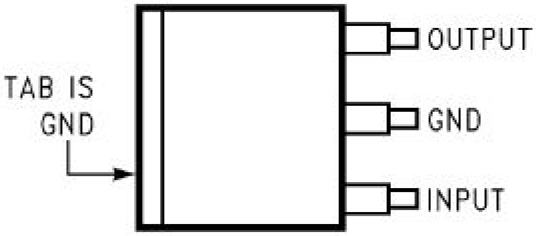
NDS Package
2-Pin TO-3
Top View



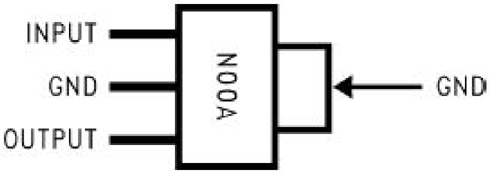
NDE Package
3-Pin TO-220
Top View



KTT Package
3-Pin DDPAK/TO-263
Top View



DCY Package
4-Pin SOT-223
Side View



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
INPUT	1	I	Input voltage pin
GND	2	I/O	Ground pin
OUTPUT	3	O	Output voltage pin

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)(2)

	MIN	MAX	UNIT
DC input voltage		35	V
Internal power dissipation(3)	Internally Limited		
Maximum junction temperature		150	°C
Storage temperature, T_{stg}	−65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

(3) The maximum allowable power dissipation at any ambient temperature is a function of the maximum junction temperature for operation (T_{JMAX} = 125°C or 150°C), the junction-to-ambient thermal resistance (θ_{JA}), and the ambient temperature (T_A). $P_{DMAX} = (T_{JMAX} - T_A)/\theta_{JA}$. If this dissipation is exceeded, the die temperature rises above T_{JMAX} and the electrical specifications do not apply. If the die temperature rises above 150°C, the device goes into thermal shutdown. For the TO-3 package (NDS), the junction-to-ambient thermal resistance (θ_{JA}) is 39°C/W. When using a heat sink, θ_{JA} is the sum of the 4°C/W junction-to-case thermal resistance (θ_{JC}) of the TO-3 package and the case-to-ambient thermal resistance of the heat sink. For the TO-220 package (NDE), θ_{JA} is 54°C/W and θ_{JC} is 4°C/W. If SOT-223 is used, the junction-to-ambient thermal resistance is 174°C/W and can be reduced by a heat sink (see Applications Hints on heat sinking).If the DDPAK\TO-263 package is used, the thermal resistance can be reduced by increasing the PCB copper area thermally connected to the package: Using 0.5 square inches of copper area, θ_{JA} is 50°C/W; with 1 square inch of copper area, θ_{JA} is 37°C/W; and with 1.6 or more inches of copper area, θ_{JA} is 32°C/W.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM)(1)	±2000	V

(1) ESD rating is based on the human-body model, 100 pF discharged through 1.5 kΩ.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Temperature (T_A)	0	125	°C

6.4 Thermal Information

THERMAL METRIC(1)		LM340-MIL				UNIT
		NDE (TO-220)	KTT (DDPAK/TO-263)	DCY (SOT-223)	NDS (TO-3)	
		3 PINS	3 PINS	4 PINS	2 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	23.9	44.8	62.1	39	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	16.7	45.6	44	2	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	5.3	24.4	10.7	—	°C/W
ψ_{JT}	Junction-to-top characterization parameter	3.2	11.2	2.7	—	°C/W
ψ_{JB}	Junction-to-board characterization parameter	5.3	23.4	10.6	—	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	1.7	1.5	—	—	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

6.5 Electrical Characteristics: V_O = 5 V, V_I = 10 V

0°C ≤ T_J ≤ 125°C unless otherwise specified[1]

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_O	Output voltage	T_J = 25°C, 5 mA ≤ I_O ≤ 1 A		4.8	5	5.2	V
		P_D ≤ 15 W, 5 mA ≤ I_O ≤ 1 A 7.5 V ≤ V_{IN} ≤ 20 V		4.75		5.25	V
ΔV_O	Line regulation	I_O = 500 mA	T_J = 25°C 7V ≤ V_{IN} ≤ 25V		3	50	mV
			Over temperature 8V ≤ V_{IN} ≤ 20V			50	mV
		I_O ≤ 1 A	T_J = 25°C 7.5V ≤ V_{IN} ≤ 20V			50	mV
			Over temperature 8V ≤ V_{IN} ≤ 12V			25	mV
ΔV_O	Load regulation	T_J = 25°C	5 mA ≤ I_O ≤ 1.5 A		10	50	mV
			250 mA ≤ I_O ≤ 750 mA			25	mV
		Over temperature, 5 mA ≤ I_O ≤ 1 A				50	mV
I_Q	Quiescent current	I_O ≤ 1 A	T_J = 25°C			8	mA
			Over temperature			8.5	mA
ΔI_Q	Quiescent current change	0°C ≤ T_J ≤ 125°C, 5 mA ≤ I_O ≤ 1 A			0.5		mA
		7 V ≤ V_{IN} ≤ 20 V	T_J = 25°C, I_O ≤ 1 A			1	mA
			Over temperature, I_O ≤ 500 mA			1	mA
V_N	Output noise voltage	T_A = 25°C, 10 Hz ≤ f ≤ 100 kHz			40		µV
$\frac{\Delta V_{IN}}{\Delta V_{OUT}}$	Ripple rejection	f = 120 Hz 8 V ≤ V_{IN} ≤ 18 V	T_J = 25°C, I_O ≤ 1 A	62	80		dB
			Over temperature, I_O ≤ 500 mA	62			dB
R_O	Dropout voltage	T_J = 25°C, I_O = 1 A			2		V
	Output resistance	f = 1 kHz			8		mΩ
	Short-circuit current	T_J = 25°C			2.1		A
	Peak output current	T_J = 25°C			2.4		A
	Average TC of V_{OUT}	Over temperature, I_O = 5 mA			−0.6		mV/°C
V_{IN}	Input voltage required to maintain line regulation	T_J = 25°C, I_O ≤ 1 A		7.5			V

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(1) All characteristics are measured with a 0.22-µF capacitor from input to ground and a 0.1-µF capacitor from output to ground. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t_w ≤ 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.

6.6 Electrical Characteristics: V_O = 12 V, V_I = 19 V

0°C ≤ T_J ≤ 125°C unless otherwise specified(1)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_O	Output voltage	T_J = 25°C, 5 mA ≤ I_O ≤ 1 A		11.5	12	12.5	V
		P_D ≤ 15 W, 5 mA ≤ I_O ≤ 1 A 14.5 V ≤ V_{IN} ≤ 27 V		11.4		12.6	V
ΔV_O	Line regulation	I_O = 500 mA	T_J = 25°C 14.5V ≤ V_{IN} ≤ 30V		4	120	mV
			Over temperature 15V ≤ V_{IN} ≤ 27V			120	mV
		I_O ≤ 1 A	T_J = 25°C 14.6V ≤ V_{IN} ≤ 27V			120	mV
			Over temperature 16V ≤ V_{IN} ≤ 22V			60	mV
ΔV_O	Load regulation	T_J = 25°C	5 mA ≤ I_O ≤ 1.5 A		12	120	mV
			250 mA ≤ I_O ≤ 750 mA			60	mV
		Over temperature, 5 mA ≤ I_O ≤ 1 A				120	mV
I_Q	Quiescent current	I_O ≤ 1 A	T_J = 25°C			8	mA
			Over temperature			8.5	mA
ΔI_Q	Quiescent current change	5 mA ≤ I_O ≤ 1 A			0.5		mA
		T_J = 25°C, I_O ≤ 1 A 14.8 V ≤ V_{IN} ≤ 27 V				1	mA
		Over temperature, I_O ≤ 500 mA 14.5 V ≤ V_{IN} ≤ 30 V				1	mA
V_N	Output noise voltage	T_A = 25°C, 10 Hz ≤ f ≤ 100 kHz			75		µV
$\frac{\Delta V_{IN}}{\Delta V_{OUT}}$	Ripple rejection	f = 120 Hz 15 V ≤ V_{IN} ≤ 25 V	T_J = 25°C, I_O ≤ 1 A	55	72		dB
			Over temperature, I_O ≤ 500 mA,	55			dB
R_O	Dropout voltage	T_J = 25°C, I_O = 1 A			2		V
	Output resistance	f = 1 kHz			18		mΩ
	Short-circuit current	T_J = 25°C			1.5		A
	Peak output current	T_J = 25°C			2.4		A
	Average TC of V_{OUT}	Over temperature, I_O = 5 mA			−1.5		mV/°C
V_{IN}	Input voltage required to maintain line regulation	T_J = 25°C, I_O ≤ 1 A		14.6			V

(1) All characteristics are measured with a 0.22-µF capacitor from input to ground and a 0.1-µF capacitor from output to ground. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t_w ≤ 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.

6.7 Electrical Characteristics: V_O = 15 V, V_I = 23 V

0°C ≤ T_J ≤ 125°C unless otherwise specified(1)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_O	Output voltage	T_J = 25°C, 5 mA ≤ I_O ≤ 1 A		14.4	15	15.6	V
		P_D ≤ 15 W, 5 mA ≤ I_O ≤ 1 A 17.5 V ≤ V_{IN} ≤ 30 V		14.25		15.75	V
ΔV_O	Line regulation	I_O = 500 mA	T_J = 25°C 17.5 V ≤ V_{IN} ≤ 30 V		4	150	mV
			Over temperature 18.5 V ≤ V_{IN} ≤ 30 V			150	mV
		I_O ≤ 1 A	T_J = 25°C 17.7 V ≤ V_{IN} ≤ 30 V			150	mV
			Over temperature 20 V ≤ V_{IN} ≤ 26 V			75	mV
ΔV_O	Load regulation	T_J = 25°C	5 mA ≤ I_O ≤ 1.5 A		12	150	mV
			250 mA ≤ I_O ≤ 750 mA			75	mV
		Over temperature, 5 mA ≤ I_O ≤ 1 A,				150	mV
I_Q	Quiescent current	I_O ≤ 1 A	T_J = 25°C			8	mA
			Over temperature			8.5	mA
ΔI_Q	Quiescent current change	5 mA ≤ I_O ≤ 1 A			0.5		mA
		T_J = 25°C, I_O ≤ 1 A 17.9 V ≤ V_{IN} ≤ 30 V				1	mA
		Over temperature, I_O ≤ 500 mA 17.5 V ≤ V_{IN} ≤ 30 V				1	mA
V_N	Output noise voltage	T_A = 25°C, 10 Hz ≤ f ≤ 100 kHz			90		μV
$\frac{\Delta V_{IN}}{\Delta V_{OUT}}$	Ripple rejection	f = 120 Hz 18.5 V ≤ V_{IN} ≤ 28.5 V	T_J = 25°C, I_O ≤ 1 A	54	70		dB
			Over temperature, I_O ≤ 500 mA,	54			dB
R_O	Dropout voltage	T_J = 25°C, I_O = 1 A			2		V
	Output resistance	f = 1 kHz			19		mΩ
	Short-circuit current	T_J = 25°C			1.2		A
	Peak output current	T_J = 25°C			2.4		A
	Average TC of V_{OUT}	Over temperature, I_O = 5 mA			−1.8		mV/°C
V_{IN}	Input voltage required to maintain line regulation	T_J = 25°C, I_O ≤ 1 A		17.7			V

(1) All characteristics are measured with a 0.22-μF capacitor from input to ground and a 0.1-μF capacitor from output to ground. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t_w ≤ 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.

6.8 Typical Characteristics

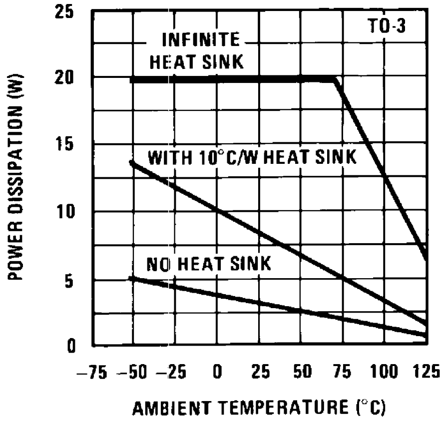


Figure 1. Maximum Average Power Dissipation

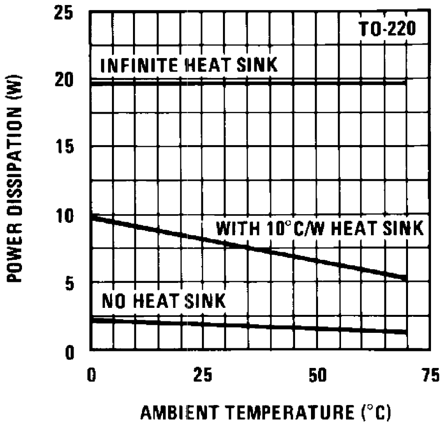


Figure 2. Maximum Average Power Dissipation

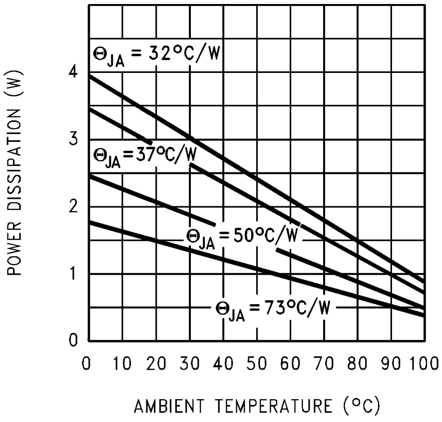
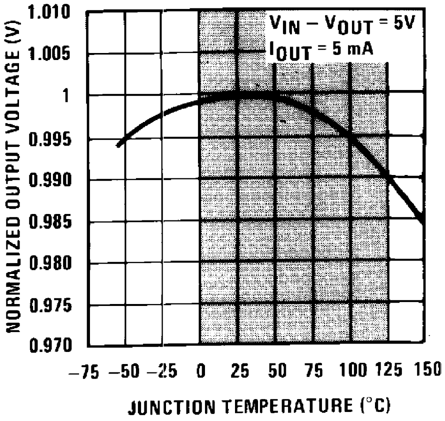


Figure 3. Maximum Power Dissipation (DDPAK/TO-263)



Shaded area refers to LM340-MIL.

Figure 4. Output Voltage (Normalized to 1 V at T_J = 25°C)

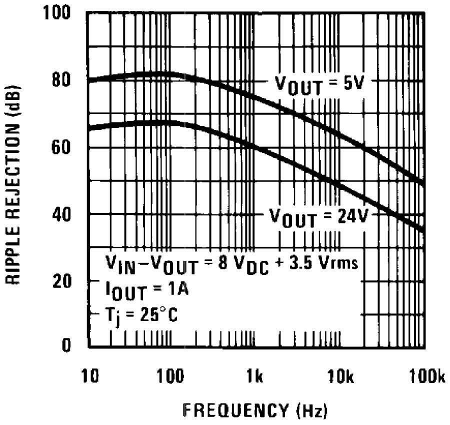


Figure 5. Ripple Rejection

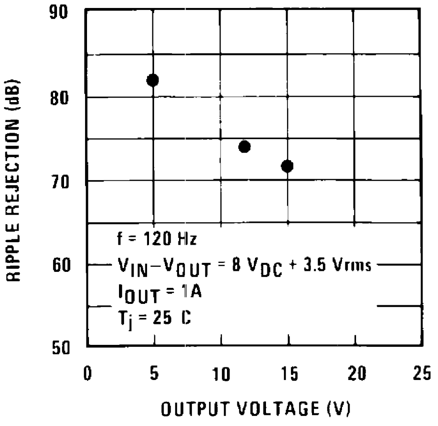


Figure 6. Ripple Rejection

Typical Characteristics (continued)

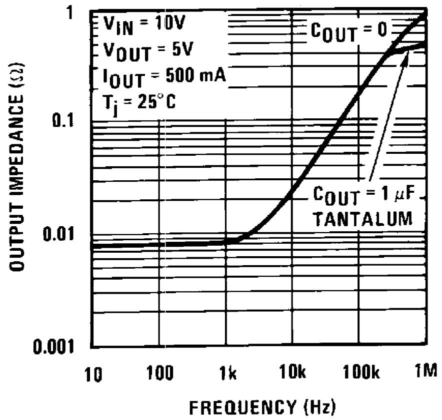


Figure 7. Output Impedance

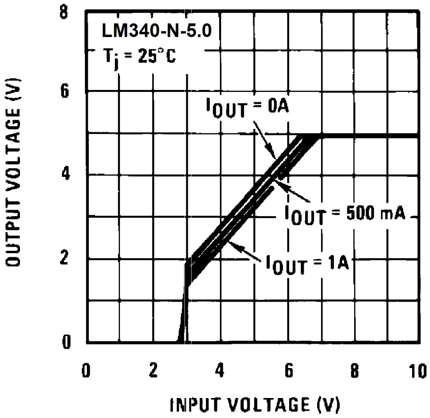
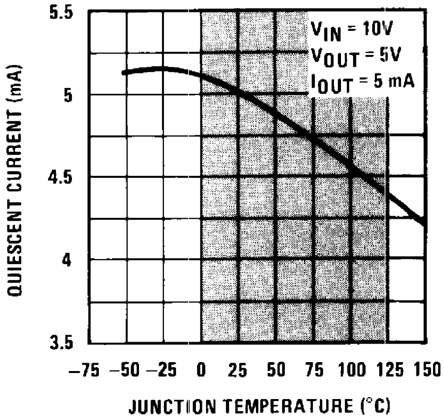


Figure 8. Dropout Characteristics



Shaded area refers to LM340-MIL.

Figure 9. Quiescent Current

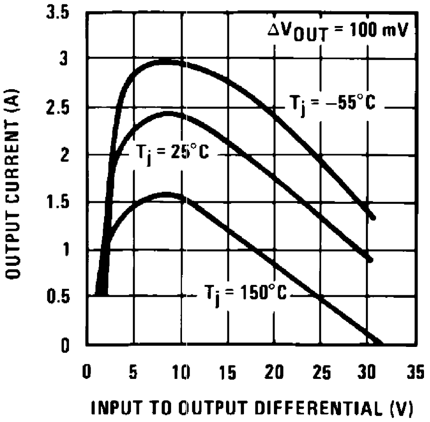
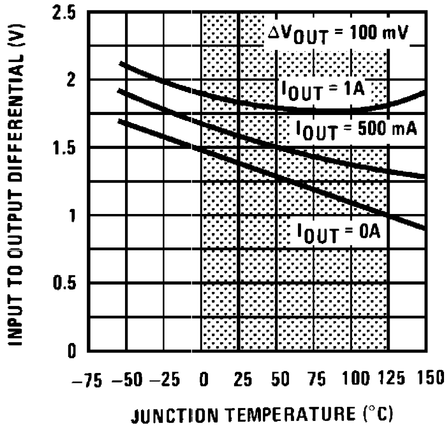


Figure 10. Peak Output Current



Shaded area refers to LM340-MIL.

Figure 11. Dropout Voltage

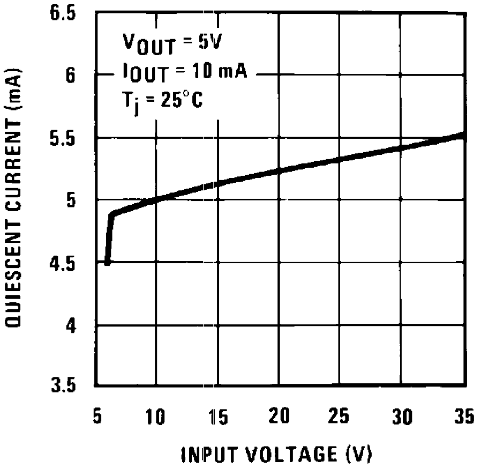
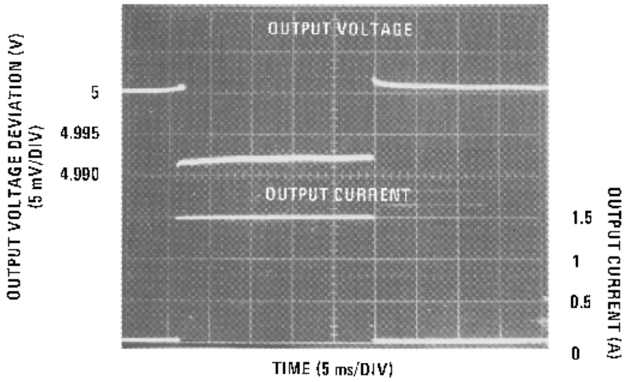


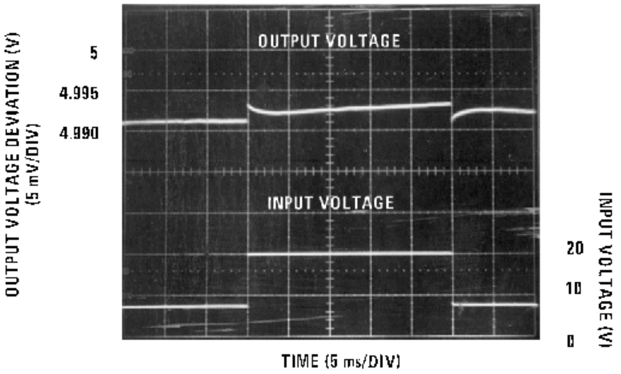
Figure 12. Quiescent Current

Typical Characteristics (continued)



I_{OUT} = 1 A, T_A = 25°C

Figure 13. Line Regulation



V_{IN} = 10 V, T_A = 25°C

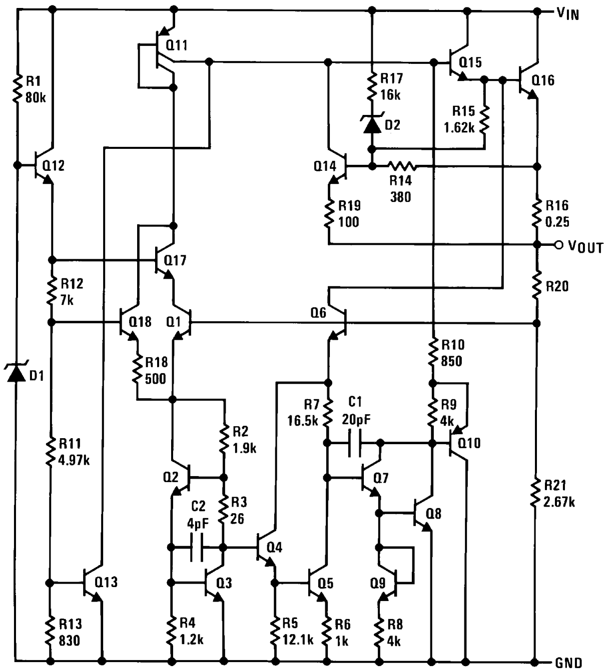
Figure 14. Line Regulation

7 Detailed Description

7.1 Overview

The LM340-MIL device is a fixed-output positive-voltage regulator with outputs ranging from 3 V to 15 V. The device accepts up to 35 V of input voltage and, with proper heat dissipation, can provide over 1.5 A of current. With a combination of current limiting, thermal shutdown, and safe area protection, this regulator helps eliminate any concern of damage. These features paired with excellent line and load regulation make the LM340-MIL device a versatile solution to a wide range of power management designs. Although the LM340-MIL device was designed primarily as fixed-voltage regulators, the device can be used with external component for adjustable voltage and current.

7.2 Functional Block Diagram



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7.3 Feature Description

7.3.1 Output Current

With proper considerations, the LM340-MIL device can exceed 1.5-A output current. Depending on the desired package option, the effective junction-to-ambient thermal resistance can be reduced through heat sinking, allowing more power to be dissipated in the device.

7.3.2 Current Limiting Feature

In the event of a short circuit at the output of the regulator, each device has an internal current limit to protect it from damage. The typical current limits for the LM340-MIL device is 2.4 A.

7.3.3 Thermal Shutdown

Each package type employs internal current limiting and thermal shutdown to provide safe operation area protection. If the junction temperature is allowed to rise to 150°C, the device will go into thermal shutdown.

7.4 Device Functional Modes

There are no functional modes for this device.

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The LM340-MIL device is designed with thermal protection, output short-circuit protection, and output transistor safe area protection. However, as with any IC regulator, it becomes necessary to take precautions to assure that the regulator is not inadvertently damaged. The following describes possible misapplications and methods to prevent damage to the regulator.

8.1.1 Shorting the Regulator Input

When using large capacitors at the output of these regulators, a protection diode connected input to output (Figure 15) may be required if the input is shorted to ground. Without the protection diode, an input short causes the input to rapidly approach ground potential, while the output remains near the initial V_{OUT} because of the stored charge in the large output capacitor. The capacitor will then discharge through a large internal input to output diode and parasitic transistors. If the energy released by the capacitor is large enough, this diode, low current metal, and the regulator are destroyed. The fast diode in Figure 15 shunts most of the capacitors discharge current around the regulator. Generally no protection diode is required for values of output capacitance ≤ 10 μF.

8.1.2 Raising the Output Voltage Above the Input Voltage

Because the output of the device does not sink current, forcing the output high can cause damage to internal low current paths in a manner similar to that just described in *Shorting the Regulator Input*.

8.1.3 Regulator Floating Ground

When the ground pin alone becomes disconnected, the output approaches the unregulated input, causing possible damage to other circuits connected to V_{OUT}. If ground is reconnected with power ON, damage may also occur to the regulator. This fault is most likely to occur when plugging in regulators or modules with on card regulators into powered up sockets. The power must be turned off first, the thermal limit ceases operating, or the ground must be connected first if power must be left on. See Figure 16.

8.1.4 Transient Voltages

If transients exceed the maximum rated input voltage of the device, or reach more than 0.8 V below ground and have sufficient energy, they will damage the regulator. The solution is to use a large input capacitor, a series input breakdown diode, a choke, a transient suppressor or a combination of these.

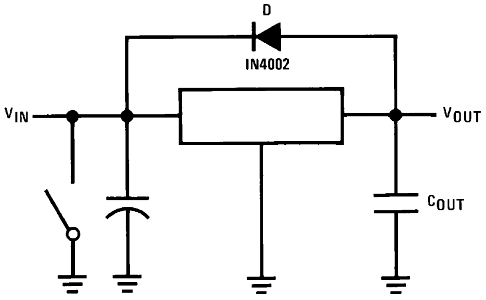


Figure 15. Input Short

Application Information (continued)

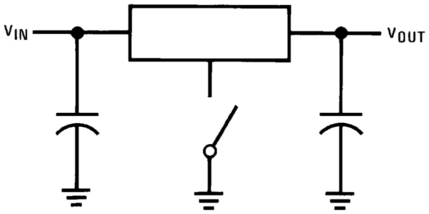


Figure 16. Regulator Floating Ground

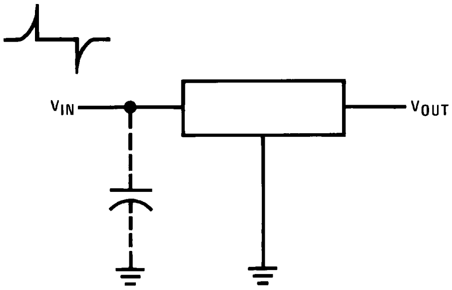


Figure 17. Transients

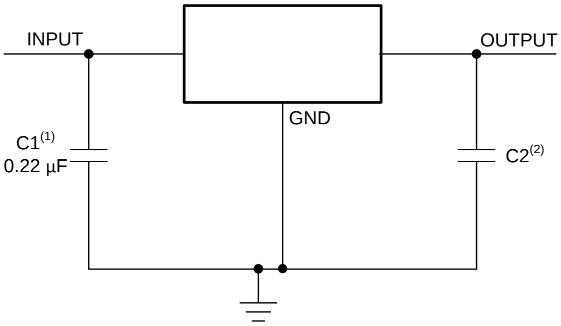
When a value for $\theta_{(H–A)}$ is found, a heat sink must be selected that has *a value that is less than or equal to this number.*

$\theta_{(H–A)}$ is specified numerically by the heat sink manufacturer in this catalog or shown in a curve that plots temperature rise vs power dissipation for the heat sink.

8.2 Typical Application

8.2.1 Fixed Output Voltage Regulator

The LM340-MIL device is primarily designed to provide fixed output voltage regulation. Figure 18 shows the simplest implementation of the LM340-MIL device.



(1) Required if the regulator is located far from the power supply filter.

(2) Although no output capacitor is needed for stability, it does help transient response. (If needed, use 0.1-μF, ceramic disc).

Figure 18. Fixed Output Voltage Regulator

Typical Application (continued)

8.2.1.1 Design Requirements

The device component count is very minimal. Although not required, TI recommends employing bypass capacitors at the output for optimum stability and transient response. These capacitors must be placed as close as possible to the regulator. If the device is located more than 6 inches from the power supply filter, it is required to employ input capacitor.

8.2.1.2 Detailed Design Procedure

The output voltage is set based on the device variant. LM340-MIL device is available in 5-V, 12-V and 15-V regulator options.

8.2.1.3 Application Curve

$V_{OUT} = 5$ V

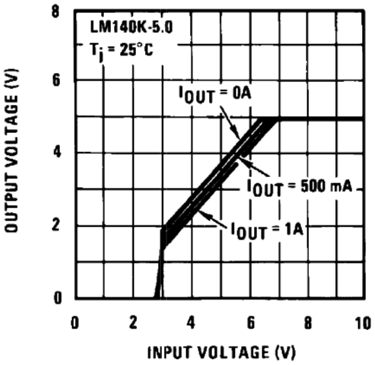
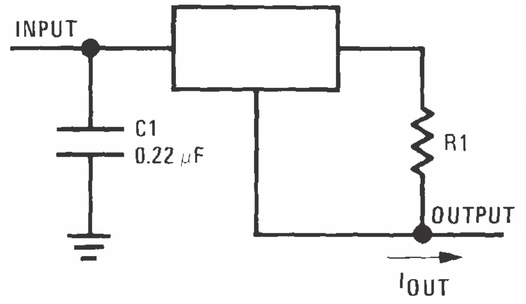


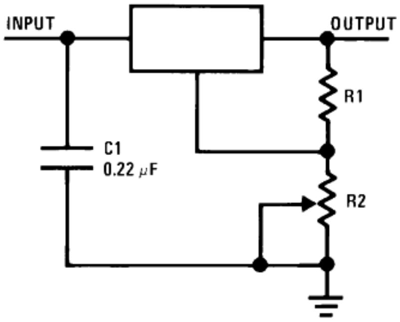
Figure 19. Output Voltage vs Input Voltage

8.3 System Examples



I_{OUT} = V2–3 / R1 + I_Q
ΔI_Q = 1.3 mA over line and load changes.

Figure 20. Current Regulator



V_{OUT} = 5 V + (5 V/R1 + I_Q)
R2 5 V/R1 > 3 I_Q, load regulation (L_r) ≈
[(R1 + R2)/R1]
(L_r of LM340-MIL-5).

Figure 21. Adjustable Output Regulator

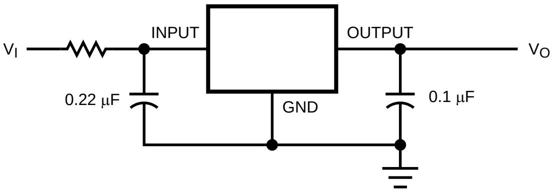


Figure 22. High Input Voltage Circuit With Series Resistor

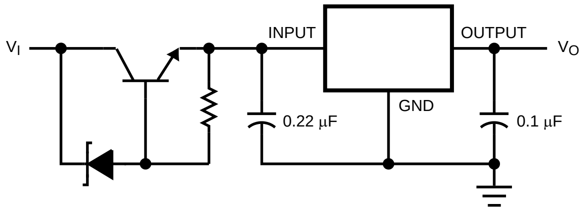
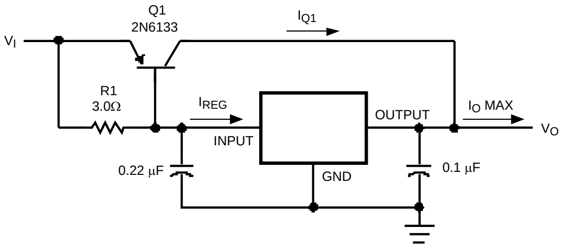
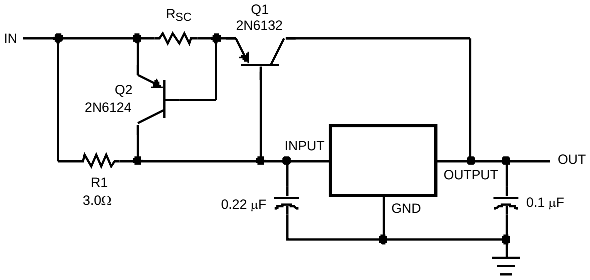


Figure 23. High Input Voltage Circuit implementation With Transistor



$\beta(Q1) \geq I_{O\ Max} / I_{REG\ Max}$
$R1 = 0.9 / I_{REG} = \beta_{(Q1)} V_{BE(Q1)} / I_{REG\ Max} (\beta + 1) - I_{O\ Max}$

Figure 24. High Current Voltage Regulator



$R_{SC} = 0.8 / I_{SC}$
$R1 = \beta V_{BE(Q1)} / I_{REG\ Max} (\beta + 1) - I_{O\ Max}$

Figure 25. High Output Current With Short-Circuit Protection

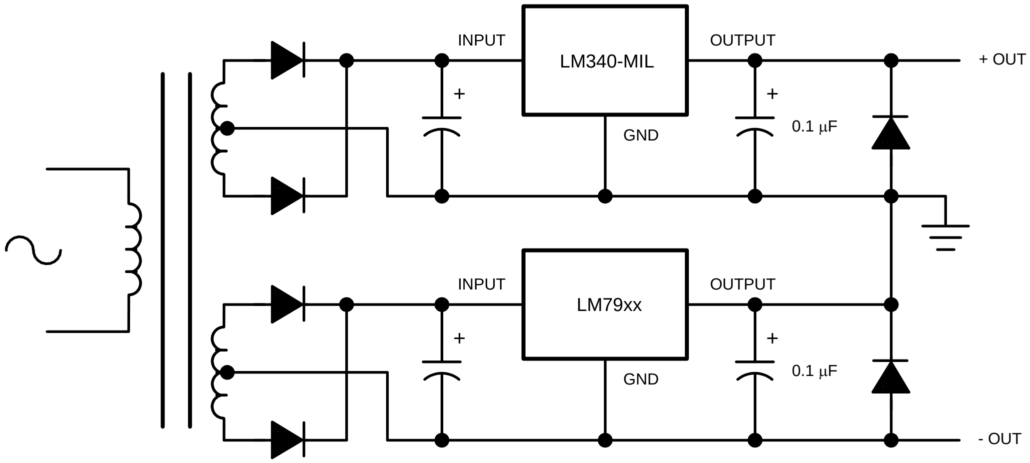


Figure 26. Device Used With Negative Regulator LM79xx

9 Power Supply Recommendations

The LM340-MIL is designed to operate from a wide input voltage up to 35 V. Please refer to electrical characteristics tables for the minimum input voltage required for line/load regulation. If the device is more than six inches from the input filter capacitors, an input bypass capacitor, 0.1 μF or greater, of any type is needed for stability.

10 Layout

10.1 Layout Guidelines

Some layout guidelines must be followed to ensure proper regulation of the output voltage with minimum noise. Traces carrying the load current must be wide to reduce the amount of parasitic trace inductance. To improve PSRR, a bypass capacitor can be placed at the OUTPUT pin and must be placed as close as possible to the IC. All that is required for the typical fixed output regulator application circuit is the LM340-MIL IC and a 0.22-µF input capacitor if the regulator is placed far from the power supply filter. A 0.1-µF output capacitor is recommended to help with transient response. In cases when VIN shorts to ground, an external diode must be placed from VOUT to VIN to divert the surge current from the output capacitor and help protect the device.

10.2 Layout Example

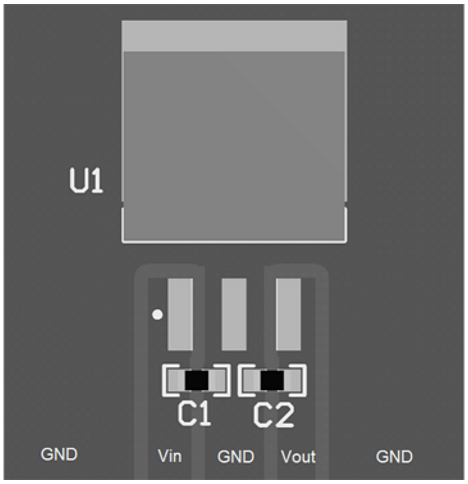


Figure 27. Layout Example DDPAK

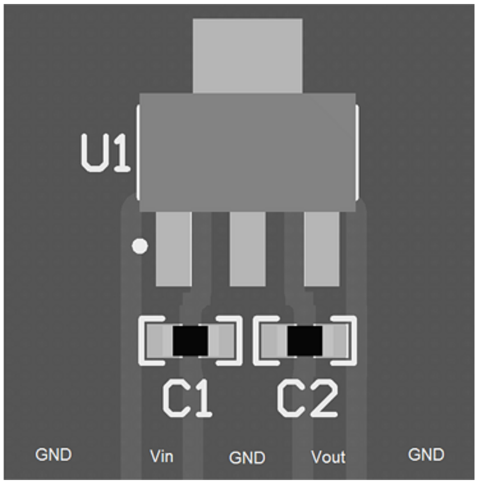


Figure 28. Layout Example SOT-223

10.3 Heat Sinking DDPAK/TO-263 and SOT-223 Package Parts

Both the DDPAK/TO-263 (KTT) and SOT-223 (DCY) packages use a copper plane on the PCB and the PCB itself as a heat sink. To optimize the heat sinking ability of the plane and PCB, solder the tab of the plane.

Figure 29 shows for the DDPAK/TO-263 the measured values of $\theta_{(J-A)}$ for different copper area sizes using a typical PCB with 1-oz copper *and no solder mask over the copper area used for heat sinking*.

As shown in Figure 29, increasing the copper area beyond 1 square inch produces very little improvement. It should also be observed that the minimum value of $\theta_{(J-A)}$ for the DDPAK/TO-263 package mounted to a PCB is 32°C/W.

As a design aid, Figure 30 shows the maximum allowable power dissipation compared to ambient temperature for the DDPAK/TO-263 device (assuming $\theta_{(J-A)}$ is 35°C/W and the maximum junction temperature is 125°C).

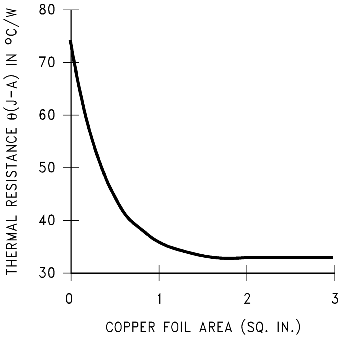


Figure 29. $\theta_{(J-A)}$ vs Copper (1 Ounce) Area for the DDPAK/TO-263 Package

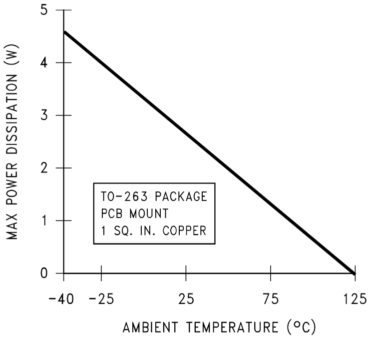


Figure 30. Maximum Power Dissipation vs T_{AMB} for the DDPAK/TO-263 Package

Figure 31 and Figure 32 show the information for the SOT-223 package. Figure 31 assumes a $\theta_{(J-A)}$ of 74°C/W for 1-oz. copper and 51°C/W for 2-oz. copper and a maximum junction temperature of 125°C.

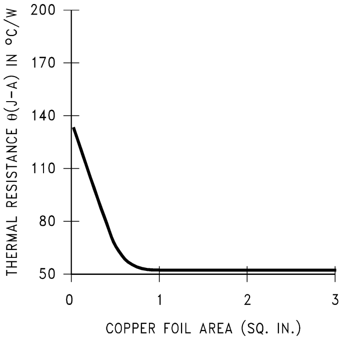


Figure 31. $\theta_{(J-A)}$ vs Copper (2 Ounce) Area for the SOT-223 Package

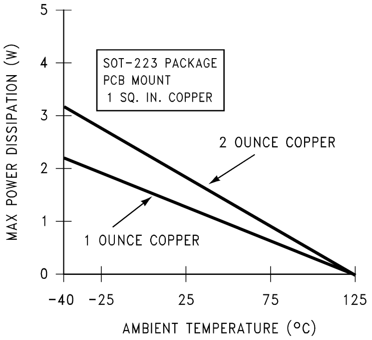


Figure 32. Maximum Power Dissipation vs T_{AMB} for the SOT-223 Package

See *AN-1028 LMX2370 PLLatinum Dual Freq Synth for RF Pers Comm LMX2370 2.5GHz/1.2GHz* for power enhancement techniques to be used with the SOT-223 package.

11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation

For related documentation see the following:

- *AN-1028 LMX2370 PLLatinum Dual Freq Synth for RF Pers Comm LMX2370 2.5GHz/1.2GHz*
- *LM79XX Series 3-pin Negative Regulators*

11.2 Receiving Notification of Documentation Updates

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11.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM340K-5.0	ACTIVE	TO-3	NDS	2	50	TBD	Call TI	Call TI	0 to 0	LM340K -5.0 7805P+	Samples
LM340K-5.0/NOPB	ACTIVE	TO-3	NDS	2	50	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	0 to 0	LM340K -5.0 7805P+	Samples

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

[3] MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

[4] There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

[5] Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

[6] Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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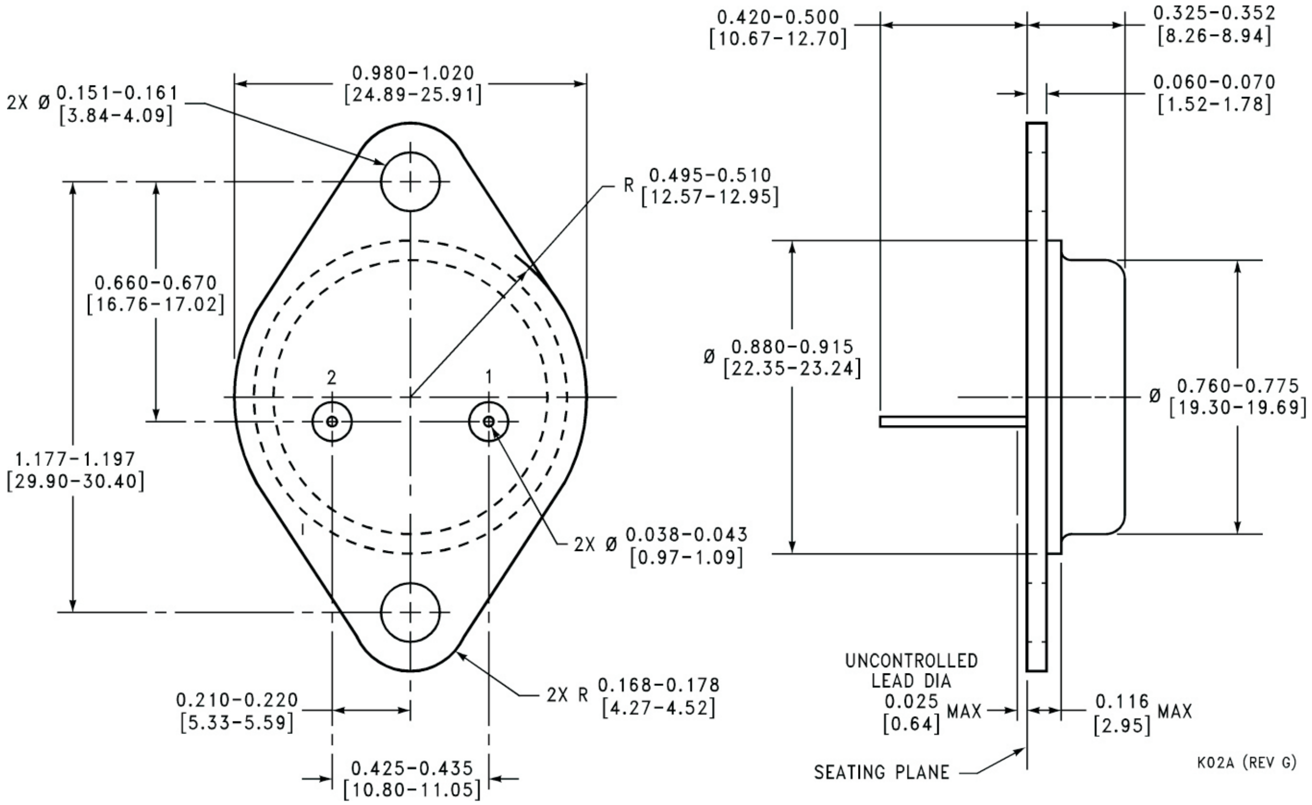
0.420-0.500
[10.67-12.70]
0.325-0.352
[8.26-8.94]
0.060-0.070
[1.52-1.78]
2X Ø 0.151-0.161
[3.84-4.09]
0.980-1.020
[24.89-25.91]
R 0.495-0.510
[12.57-12.95]
0.660-0.670
[16.76-17.02]
Ø 0.880-0.915
[22.35-23.24]
Ø 0.760-0.775
[19.30-19.69]
2
1
1.177-1.197
[29.90-30.40]
2X Ø 0.038-0.043
[0.97-1.09]
UNCONTROLLED
LEAD DIA
0.025
[0.64] MAX
0.116
[2.95] MAX
0.210-0.220
[5.33-5.59]
2X R 0.168-0.178
[4.27-4.52]
0.425-0.435
[10.80-11.05]
SEATING PLANE
K02A (REV G)

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